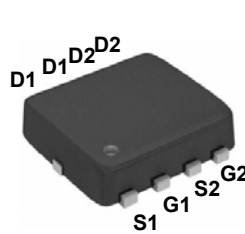
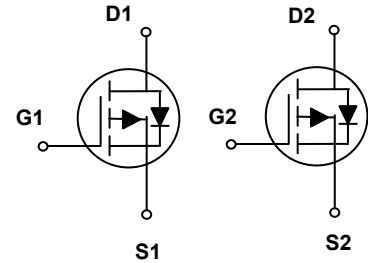


### Main Product Characteristics

$V_{(BR)DSS}$	-20V
$R_{DS(ON)}$	33m $\Omega$ (Max.)
$I_D$	-7.5A



PPAK3x3



Schematic Diagram

### Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



### Description

The GSFN0207 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supply and a wide variety of other applications.

### Absolute Maximum Ratings (T<sub>C</sub>=25°C unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V <sub>DS</sub>	-20	V
Gate-Source Voltage	V <sub>GS</sub>	±12	V
Drain Current-Continuous (T <sub>C</sub> =25°C)	I <sub>D</sub>	-7.5	A
Drain Current-Continuous (T <sub>C</sub> =100°C)		-4.5	A
Drain Current-Pulsed <sup>1</sup>	I <sub>DM</sub>	-30	A
Power Dissipation (T <sub>C</sub> =25°C)	P <sub>D</sub>	25	W
Power Dissipation – Derate above 25°C		0.2	W/°C
Max. Thermal Resistance Junction to Ambient	R <sub>θJA</sub>	62	°C/W
Max. Thermal Resistance Junction to Case	R <sub>θJC</sub>	5	°C/W
Storage Temperature Range	T <sub>STG</sub>	-55 to +150	°C
Operating Junction Temperature Range	T <sub>J</sub>	-55 to +150	°C

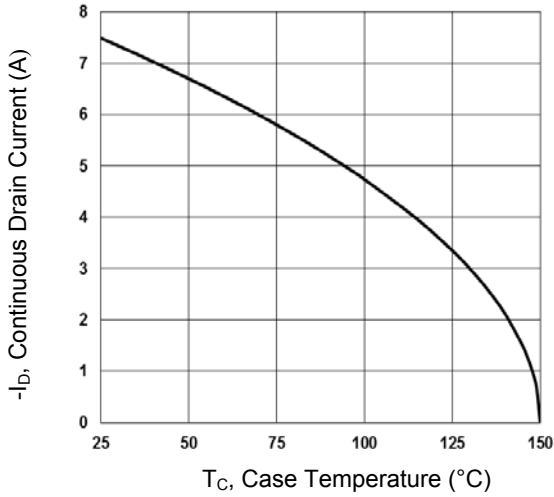
### Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =-250uA	-20	-	-	V
BV <sub>DSS</sub> Temperature Coefficient	ΔBV <sub>DSS</sub> /ΔT <sub>J</sub>	Reference to 25°C, I <sub>D</sub> =-1mA	-	-0.02	-	V/°C
Drain-Source Leakage Current	I <sub>DSS</sub>	V <sub>DS</sub> =-20V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	-	-	-1	uA
		V <sub>DS</sub> =-16V, V <sub>GS</sub> =0V, T <sub>J</sub> =125°C	-	-	-10	uA
Gate-Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±10V, V <sub>DS</sub> =0V	-	-	±100	nA
<b>On Characteristics</b>						
Static Drain-Source On-Resistance <sup>2</sup>	R <sub>DS(ON)</sub>	V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-4A	-	28	33	mΩ
		V <sub>GS</sub> =-2.5V, I <sub>D</sub> =-3A	-	37	45	mΩ
		V <sub>GS</sub> =-1.8V, I <sub>D</sub> =-2A	-	49	65	mΩ
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =-250uA	-0.3	-0.6	-1	V
V <sub>GS(th)</sub> Temperature Coefficient	ΔV <sub>GS(th)</sub>		-	2	-	mV/°C
Forward Transconductance	g <sub>fs</sub>	V <sub>DS</sub> =-10V, I <sub>D</sub> =-3A	-	8.5	-	S
<b>Dynamic and Switching Characteristics</b>						
Total Gate Charge <sup>3</sup>	Q <sub>g</sub>	V <sub>DS</sub> =-10V, V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-4A	-	16.1	25	nC
Gate-Source Charge <sup>3</sup>	Q <sub>gs</sub>		-	1.8	3.6	
Gate-Drain Charge <sup>3</sup>	Q <sub>gd</sub>		-	3.8	7	
Turn-On Delay Time <sup>3</sup>	t <sub>d(on)</sub>	V <sub>DD</sub> =-10V, V <sub>GS</sub> =-4.5V, R <sub>G</sub> =25Ω, I <sub>D</sub> =1A	-	8.2	16	nS
Rise Time <sup>3</sup>	t <sub>r</sub>		-	30	57	
Turn-Off Delay Time <sup>3</sup>	t <sub>d(off)</sub>		-	71	135	
Fall Time <sup>3</sup>	t <sub>f</sub>		-	20	38	
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =-15V, V <sub>GS</sub> =0V, F=1MHz	-	1440	2100	pF
Output Capacitance	C <sub>oss</sub>		-	155	230	
Reverse Transfer Capacitance	C <sub>rss</sub>		-	115	170	
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Continuous Source Current	I <sub>S</sub>	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	-	-	-7.5	A
Pulsed Source Current <sup>2</sup>	I <sub>SM</sub>		-	-	-15	A
Diode Forward Voltage <sup>2</sup>	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =-1A, T <sub>J</sub> =25°C	-	-	-1	V

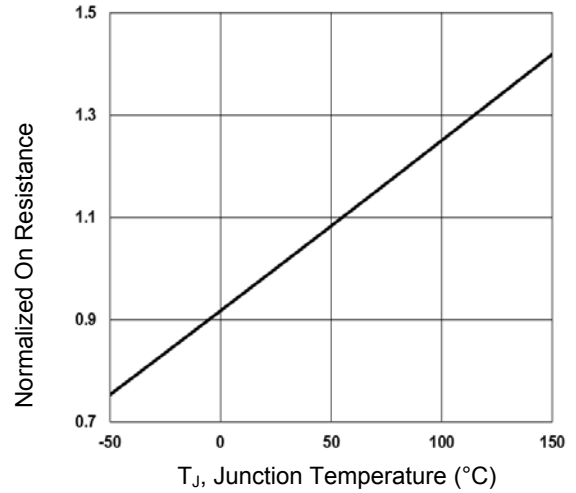
Note:

1. Repetitive Rating: Pulsed width limited by maximum junction temperature.
2. Pulsed tested: pulse width ≤ 300us, duty cycle ≤ 2%.
3. Essentially independent of operating temperature.

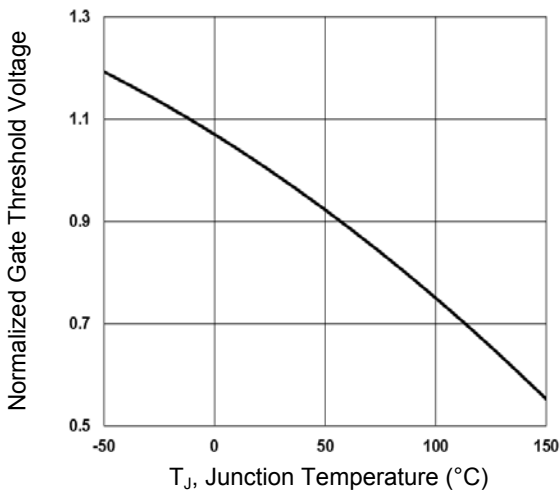
### Typical Electrical and Thermal Characteristic Curves



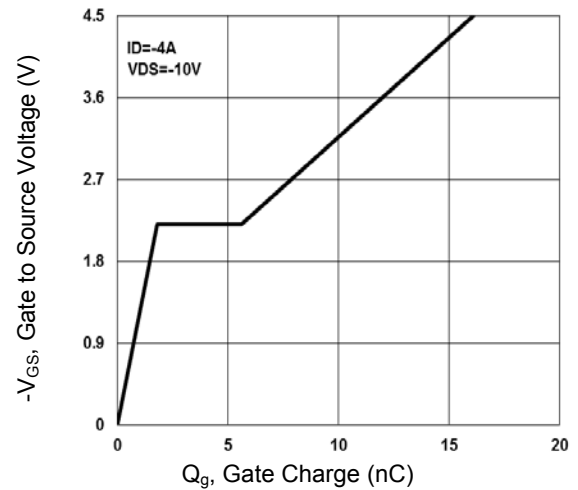
**Figure 1. Continuous Drain Current vs.  $T_C$**



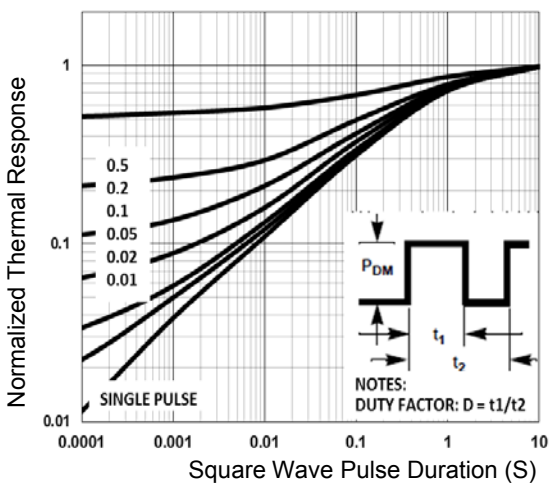
**Figure 2. Normalized  $R_{DS(ON)}$  vs.  $T_J$**



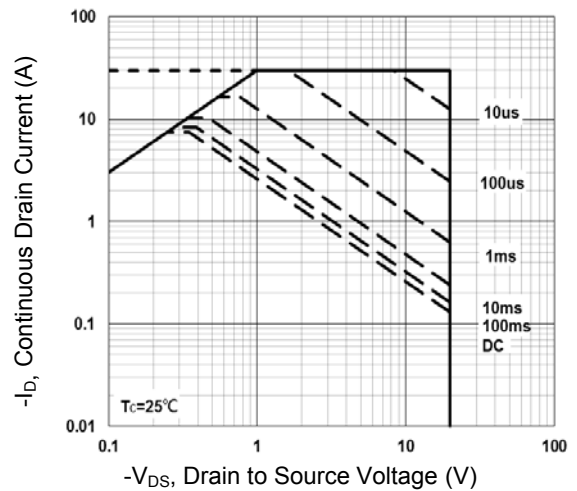
**Figure 3. Normalized  $V_{th}$  vs.  $T_J$**



**Figure 4. Gate Charge Waveform**

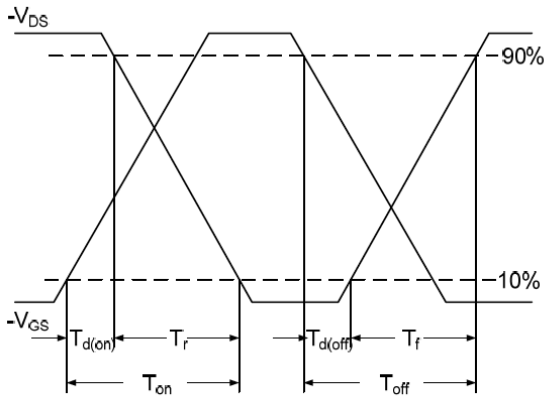


**Figure 5. Normalized Transient Response**

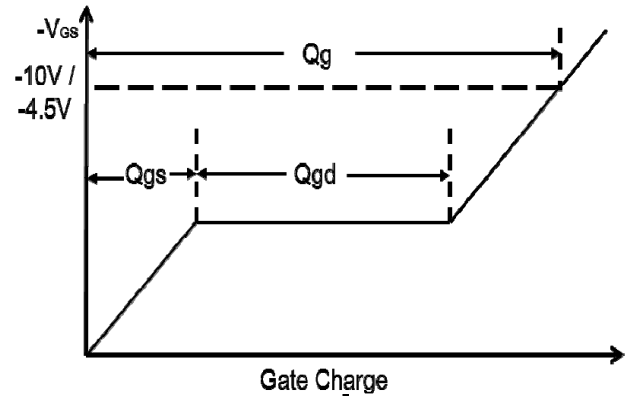


**Figure 6. Maximum Safe Operation Area**

**Typical Electrical and Thermal Characteristic Curves**

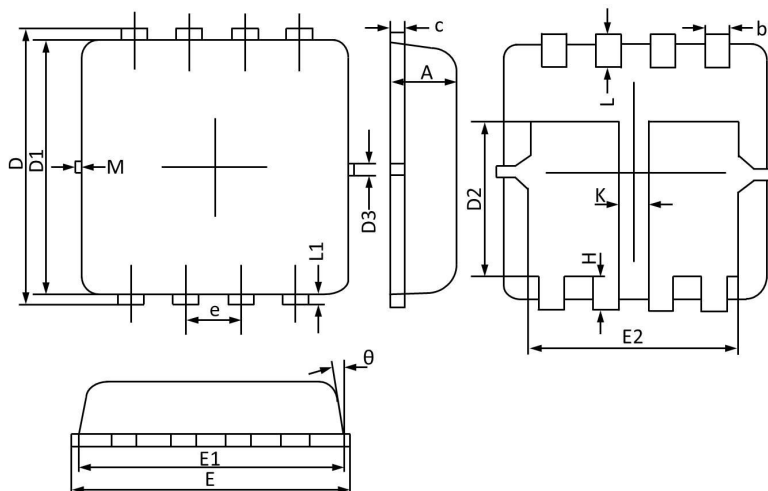


**Figure 7. Switching Time Waveform**



**Figure 8. Gate Charge Waveform**

### Package Outline Dimensions (PPAK3X3)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.670	0.880	0.026	0.035
b	0.250	0.350	0.010	0.014
c	0.100	0.250	0.004	0.010
D	3.150	3.550	0.124	0.140
D1	3.000	3.300	0.118	0.130
D2	1.500	2.000	0.059	0.079
D3	0.130	0.200	0.005	0.008
E	3.100	3.500	0.122	0.138
E1	3.000	3.200	0.118	0.126
E2	2.350	2.600	0.093	0.102
e	0.650 BSC		0.026 BSC	
H	0.300	0.500	0.012	0.020
L	0.300	0.500	0.012	0.020
L1	0.130 REF		0.005 REF	
K	0.300 REF		0.012 REF	
θ	0°	12°	0°	12°
M	0.150 REF		0.006 REF	

### Order Information

Device	Package	Marking	Carrier	Quantity
GSFN0207	PPAK3x3	DC2209V	Tape & Reel	3,000 Pcs / Reel